Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	(("6048755") or ("6077757") or ("6100114") or ("6207478") or ("20010018229")).PN.	US-PGPUB; USPAT	OR	OFF	2005/12/14 20:42
L2	68814	chip$1.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:42
L3	2397	2 and (plastic near2 mold$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:49
L4	1076	3 and (packag$3 or encapsulat$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:49
L5	238	4 and ((edge$1 or back) near3 side$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:50
L6	104	5 and plastic.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:50
L7	90	6 and first and second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:51
L8	72	6 and first.clm. and second.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:51
L9	175	5 and semiconductor.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 20:51
L10	53	8 and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:07

L11	13640	(semiconductor adj chip$1).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:08
L12	4388	11 and back and side$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:08
L13	2842	12 and ((packag$3 or encapsulat$3 or enclos$3 or surround$3) near5 chip$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:11
L14	1667	13 and (plastic or molding or mold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:11
L15	1119	14 and (edge$1.clm. or side.clm. or back.clm.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:10
L16	470	15 and (first near6 (package or molding or plastic))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:10
L17	183	16 and (plastic or molding or mold). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:11
L18	109	17 and ((packag$3 or encapsulat$3 or enclos$3 or surround$3) near5 chip$1).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:19
L19	19	17 and (plastic near2 molding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 21:19